

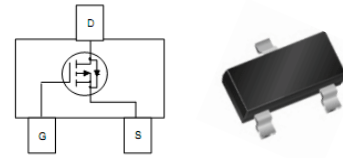
**P-Channel Enhancement MOSFET**

**RoHS Device  
Halogen Free**

**■ Features**

- Ultra Low On-Resistance
- P-Channel MOSFET
- SOT-23 Footprint
- Low Profile (<1.1mm)
- Available in Tape and Reel
- Fast Switching

SOT-23


**■ MAXIMUM RATINGS**

Characteristic	Symbol	Max	Unit
Drain-Source Voltage	$BV_{DSS}$	-12	V
Gate- Source Voltage	$V_{GS}$	$\pm 8$	V
Drain Current (continuous)	$I_D$	-4.3	A
Drain Current (pulsed)	$I_{DM}$	-13	A
Total Device Dissipation $T_A=25^\circ\text{C}$	PD	1300	mW
Junction	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55to+150	$^\circ\text{C}$

**P-Channel Enhancement MOSFET**
**■ ELECTRICAL CHARACTERISTICS**

(TA=25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage ( $I_D = -250\mu A, V_{GS} = 0V$ )	$BV_{DSS}$	-12	—	—	V
Gate Threshold Voltage ( $I_D = -250\mu A, V_{GS} = V_{DS}$ )	$V_{GS(th)}$	-0.4	—	-0.95	V
Zero Gate Voltage Drain Current ( $V_{GS} = 0V, V_{DS} = -12V$ ) ( $V_{GS} = 0V, V_{DS} = -9.6V, T_A = 55^\circ C$ )	$I_{DSS}$	—	—	-1 -25	$\mu A$
Gate Body Leakage ( $V_{GS} = \pm 8V, V_{DS} = 0V$ )	$I_{GSS}$	—	—	$\pm 100$	nA
Static Drain-Source On-State Resistance ( $I_D = -4.3A, V_{GS} = -4.5V$ )	$R_{DS(ON)}$	—	—	50	$m\Omega$
Static Drain-Source On-State Resistance ( $I_D = -2.5A, V_{GS} = -2.5V$ )	$R_{DS(ON)}$	—	—	85	$m\Omega$
Static Drain-Source On-State Resistance ( $I_D = -2A, V_{GS} = -1.8V$ )	$R_{DS(ON)}$	—	—	125	$m\Omega$
Input Capacitance ( $V_{GS} = 0V, V_{DS} = -10V, f = 1MHz$ )	$C_{ISS}$	—	830	—	pF
Output Capacitance ( $V_{GS} = 0V, V_{DS} = -10V, f = 1MHz$ )	$C_{OSS}$	—	180	—	pF
Turn-ON Time ( $V_{DS} = -6V, I_D = -1A, R_{GEN} = 6\Omega$ )	$t_{(on)}$	—	11	—	ns
Turn-OFF Time ( $V_{DS} = -6V, I_D = -1A, R_{GEN} = 6\Omega$ )	$t_{(off)}$	—	250	—	ns

 Pulse Width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2.0\%$

# P-Channel Enhancement MOSFET

## TYPICAL CHARACTERISTICS

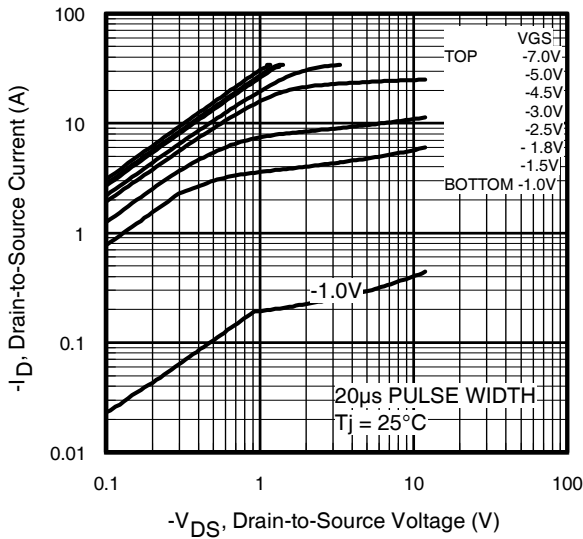


Fig 1. Typical Output Characteristics

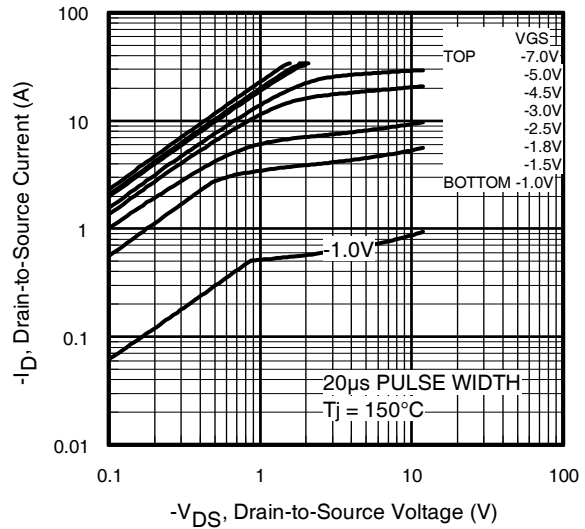


Fig 2. Typical Output Characteristics

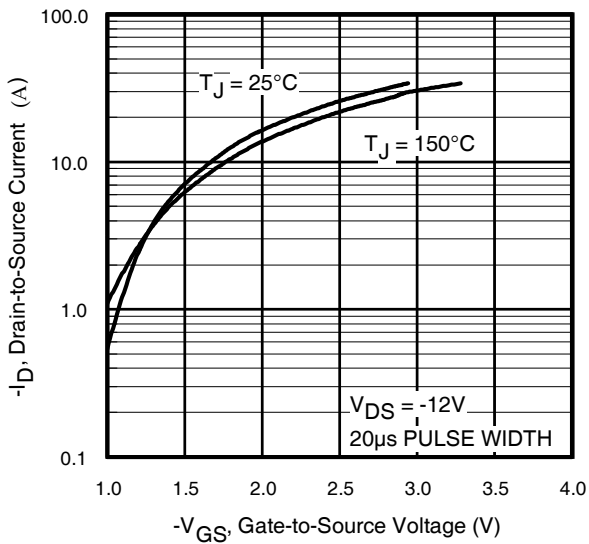


Fig 3. Typical Transfer Characteristics

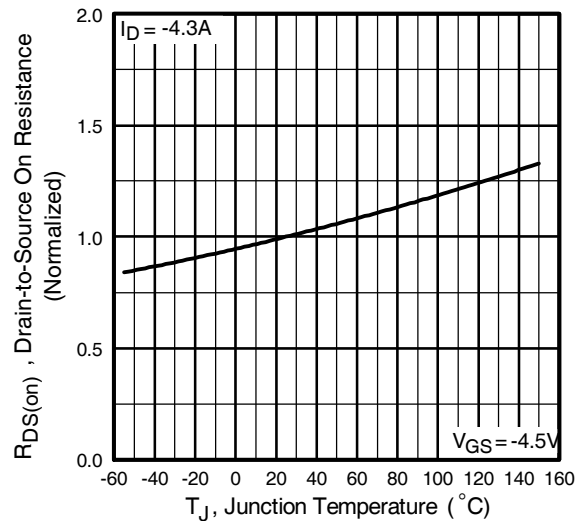
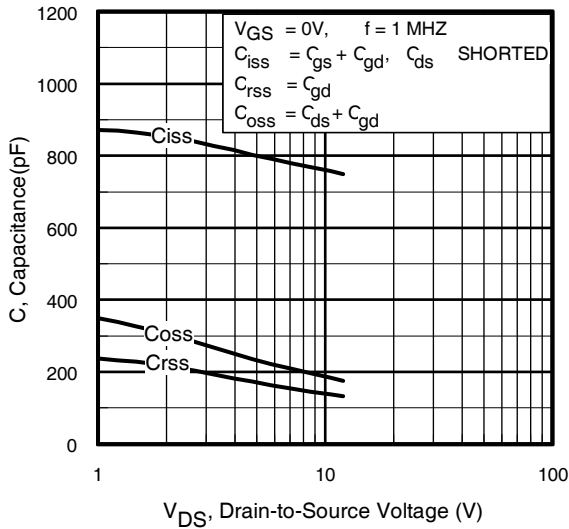
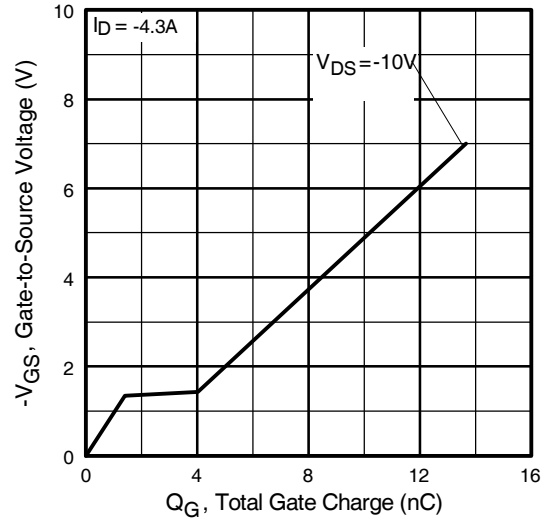
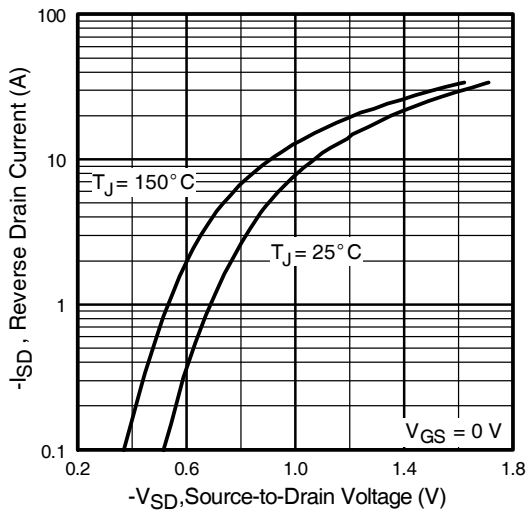
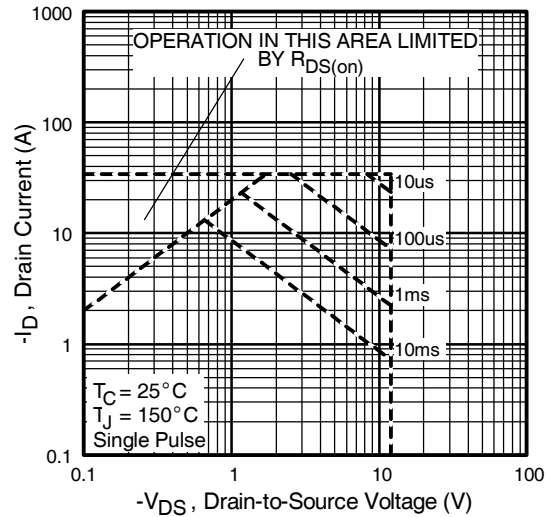
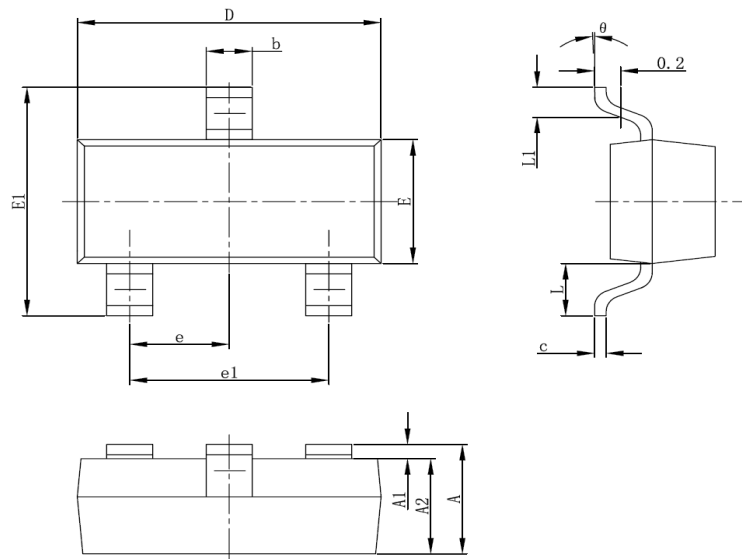


Fig 4. Normalized On-Resistance Vs. Temperature

**P-Channel Enhancement MOSFET**

**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage

**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage

**Fig 7.** Typical Source-Drain Diode Forward Voltage

**Fig 8.** Maximum Safe Operating Area

**P-Channel Enhancement MOSFET**
**■ SOT-23 PACKAGE OUTLINE**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°